

# MOS FIELD EFFECT TRANSISTOR 2SK3993

# SWITCHING N-CHANNEL POWER MOS FET

#### **DESCRIPTION**

The 2SK3993 is N-channel MOS FET device that features a low on-state resistance and excellent switching characteristics, and designed for low voltage high current applications such as DC/DC converter with synchronous rectifier.

#### **ORDERING INFORMATION**

PART NUMBER	PACKAGE
2SK3993	TO-251 (MP-3)
2SK3993-ZK	TO-252 (MP-3ZK)

**FEATURES** 

- Low on-state resistance
   R<sub>DS(on)1</sub> = 3.8 mΩ MAX. (V<sub>GS</sub> = 10 V, I<sub>D</sub> = 32 A)
- Low Ciss: Ciss = 4770 pF TYP.
- 5 V drive available

(TO-251)



(TO-252)



#### ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage (Vgs = 0 V)	VDSS	25	V
Gate to Source Voltage (VDS = 0 V)	Vgss	±20	V
Drain Current (DC) (Tc = 25°C)	ID(DC)	±64	Α
Drain Current (pulse) Note1	ID(pulse)	±256	Α
Total Power Dissipation (Tc = 25°C)	P <sub>T1</sub>	40	W
Total Power Dissipation	P <sub>T2</sub>	1.0	W
Channel Temperature	Tch	150	°C
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C
Single Avalanche Current Note2	las	41	Α
Single Avalanche Energy Note2	Eas	168	mJ

**Notes 1.** PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1%

2. Starting T<sub>ch</sub> = 25°C, V<sub>DD</sub> = 12.5 V, R<sub>G</sub> = 25  $\Omega$ , V<sub>GS</sub> = 20  $\rightarrow$  0 V

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#### **ELECTRICAL CHARACTERISTICS (TA = 25°C)**

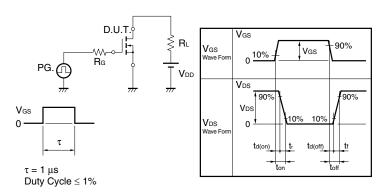
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V			10	μΑ
Gate Leakage Current	Igss	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V			±100	nA
Gate Cut-off Voltage	V <sub>GS(off)</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	2.4	3.0	V
Forward Transfer Admittance Note	y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 16 A	15			s
Drain to Source On-state Resistance Note	R <sub>DS(on)1</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 32 A		2.7	3.8	mΩ
	R <sub>DS(on)2</sub>	V <sub>GS</sub> = 5.0 V, I <sub>D</sub> = 16 A		4.1	7.8	mΩ
Input Capacitance	Ciss	V <sub>DS</sub> = 10 V		4770		pF
Output Capacitance	Coss	V <sub>GS</sub> = 0 V		1000		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		690		pF
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 12.5 V, I <sub>D</sub> = 32 A		27		ns
Rise Time	tr	V <sub>GS</sub> = 10 V		38		ns
Turn-off Delay Time	td(off)	R <sub>G</sub> = 10 Ω		107		ns
Fall Time	<b>t</b> f			54		ns
Total Gate Charge	Q <sub>G</sub>	V <sub>DD</sub> = 20 V		88		nC
Gate to Source Charge	Q <sub>GS</sub>	V <sub>GS</sub> = 10 V		16		nC
Gate to Drain Charge	Q <sub>GD</sub>	I <sub>D</sub> = 64 A		30		nC
Body Diode Forward Voltage Note	V <sub>F(S-D)</sub>	I <sub>F</sub> = 64 A, V <sub>GS</sub> = 0 V		0.91		V
Reverse Recovery Time	trr	I <sub>F</sub> = 64 A, V <sub>GS</sub> = 0 V		43		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		52		nC

Note Pulsed

#### **TEST CIRCUIT 1 AVALANCHE CAPABILITY**

# $V_{GS} = 20 \rightarrow 0 \text{ V}$ $PG. \quad PG. \quad V_{DD}$ $PG. \quad V_{DD}$

#### TEST CIRCUIT 2 SWITCHING TIME



#### **TEST CIRCUIT 3 GATE CHARGE**

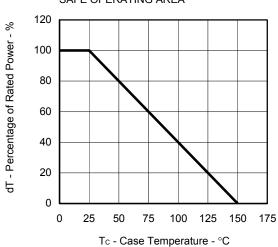
$$\begin{array}{c|c} D.U.T. \\ \hline \\ I_G = 2 \text{ mA} \\ \hline \\ V_{DD} \end{array}$$

-Starting Tch

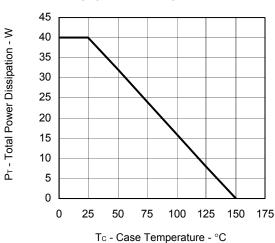


#### TYPICAL CHARACTERISTICS (TA = 25°C)

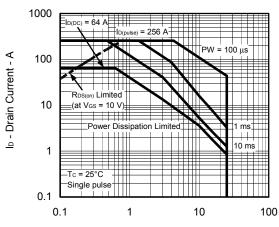
# DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



# TOTAL POWER DISSIPATION vs. CASE TEMPERATURE

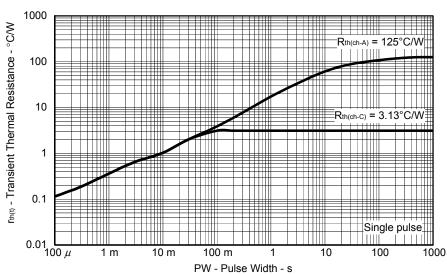


#### FORWARD BIAS SAFE OPERATING AREA





#### TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

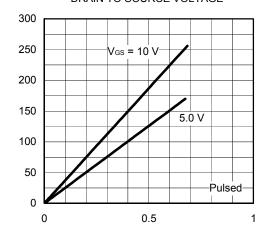


3

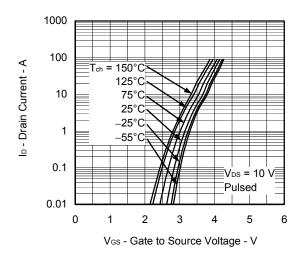
lo - Drain Current - A

VGS(off) - Gate Cut-off Voltage - V

#### DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE

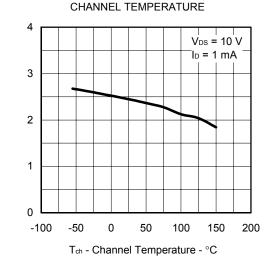


#### FORWARD TRANSFER CHARACTERISTICS

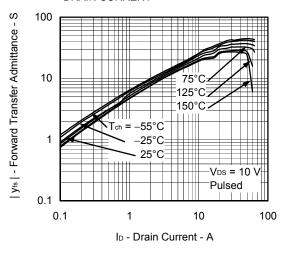


#### GATE CUT-OFF VOLTAGE vs.

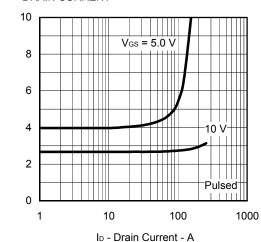
VDS - Drain to Source Voltage - V



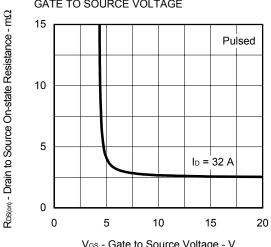
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



#### DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



#### DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



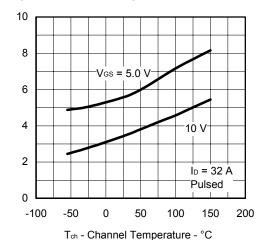
V<sub>GS</sub> - Gate to Source Voltage - V

R<sub>DS(on)</sub> - Drain to Source On-state Resistance - mΩ

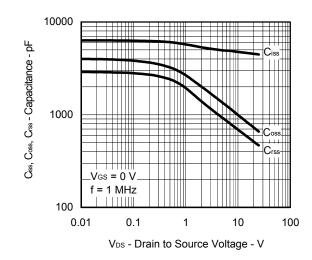


RDS(on) - Drain to Source On-state Resistance - m\Omega

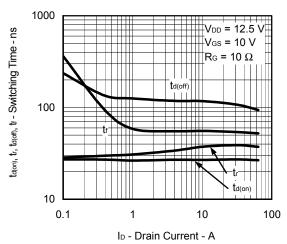
### DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



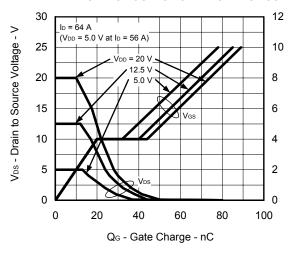
#### CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



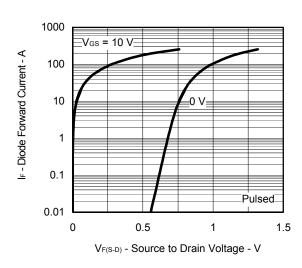
#### SWITCHING CHARACTERISTICS



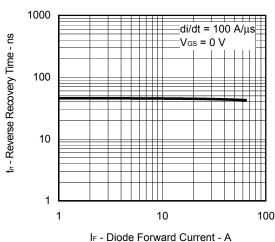
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



#### SOURCE TO DRAIN DIODE FORWARD VOLTAGE

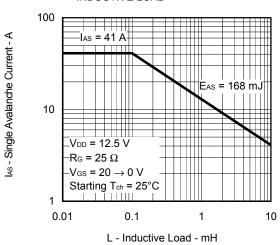


## REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT

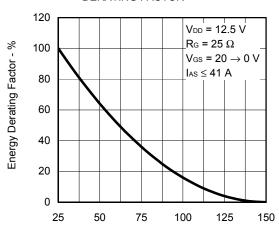


Vgs - Gate to Source Voltage - V

# SINGLE AVALANCHE CURRENT vs. INDUCTIVE LOAD



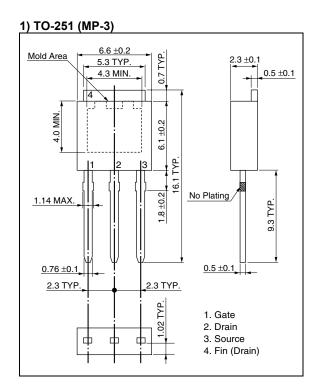
# SINGLE AVALANCHE ENERGY DERATING FACTOR

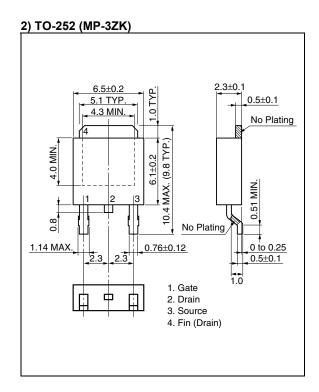


Starting  $T_{\text{ch}}$  - Starting Channel Temperature - °C

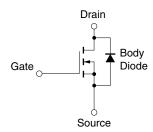


#### PACKAGE DRAWINGS (Unit: mm)





#### **EQUIVALENT CIRCUIT**



**Remark** Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

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